SOUDAL

Technical Data Sheet

MS-20 Plus

Technical data

Basis	Silane polymer
Consistency	Paste
Curing system	Chemical curing
Density	Ca. 1,75 g/ml
Temperature resistance**	-40 °C till +90 °C (cured)
Open time (23°C, 55% RV)*	25 - 30 minutes
Adjustable until	25 - 30 minutes
Shear strength**	> 1,00 N/mm²
Can be loaded after*	min. 8h
Sandable/Paintable after	min. 24h
Resistance against aging	Good
Application temperature	15 °C → 25 °C
Consumption*	Depending on the surface and trowel Adhesive trowel B3: 700 - 900 g/m² Trowel B11: 900 - 1200 g/m²

* These values may vary depending on environmental factors such as temperature, moisture, and type of substrates. ** This information relates to fully cured product.

Product description
MS-20 Plus is a high elastic, solvent, and water-free universal parquet adhesive. Suitable for bonding engineered and solid parquet with tooth and groove onto suitable indoor subfloors.

Properties
- Flexible
- EC-1 Plus label: very low emission
- 1-component system ready for use
- Solvent free
- Contains no water
- Free of isocyanate
- Easy application
- Suitable for underfloor heating

Applications
- MS-20 Plus is a parquet adhesive suitable for bonding of both engineered and solid parquet with tooth and groove.
- Solid parquet with a maximum width of 160mm and a minimal thickness of 14mm.
- Engineered parquet with a maximum width of 220mm and a minimal thickness of 14mm.

Packaging
Colour: light brown
Packaging: 6 kg bucket, 14kg (2 alu bags in box), 16 kg bucket, 18kg (3 alu-bags in bucket)

Shelf life
16kg bucket, at least 9 months in unopened packaging in a dry storage place at temperatures between +5 °C and +25 °C. Alu bags: 12 months in unopened packaging in a cool and dry storage place at temperatures between +5°C and +25°C.

Substrates
Nature: MS-20 Plus should be applied on a rigid, clean, permanently dry, dust and grease free surface which do not contain any loose parts, paint, wax, oil or other contaminants. Irregularities such as remaining concrete leveling, old adhesives may adversely affect adhesion. These need preferably to be removed mechanically for example by sanding or blasting. The top layer of anhydrite subfloors has to be removed.
Before installation of the parquet, the substrate should be checked to ensure it is suitable.

Check the moisture content throughout the entire thickness of the substrate with a carbide or electric hygrometer. Note that an electric hygrometer only gives indicative values. The moisture content must correspond the recommendation of the floor manufacturer (generally max. 2% for sand cement substrates and max. 0,5% for anhydrite, measured with a carbide hygrometer. For substrates with underfloorheating the values are resp. max. 1,5% and 0,3%). We recommend a preliminary adhesion test on any substrate.

Parquet
The parquet flooring must be acclimatised for several days in the area where it is to be installed. Leave the parquet in its original packaging until installation to avoid any deformation. Check before installation that the moisture content of the wood is as recommended by the supplier, (generally 9% +/- 2%). If the humidity of the wood is more than 11% installation is not recommended. Allow a gap of 1 to 1,5 cm around the perimeter of the laid parquet, including any columns or structures, which penetrate the floor.

Application method
MS-20 Plus should be acclimatised to room temperature before installation. Apply the adhesive by means of Soudal notched trowel B11 to the surface. Do not apply more to the surface than can be covered with parquet within 30 minutes. Slide the parquet onto the adhesive layer and tap into place or tamp down with a rubber hammer. A minimum of 80% contact coverage is required to ensure the adhesion of ther parquet. If necessary load the parquet with weight. Wait at least 24 hours before sanding and finishing the parquet.
Cleaning: MS-20 Plus can be removed before curing from tools and material with Soudal Adhesive Cleaner 90A, Swipex or white spirit. Cured MS-20 Plus can only be removed mechanically.

Health- and Safety Recommendations
Take the usual labour hygiene into account. Consult label and material safety data sheet for more information.

Remarks
- Minimum temperature of the substrate should be at least 15°C.
- Do not apply the adhesive when the relative humidity is above 75%.
- Never install flooring on a substrate which contains too much moisture or on substrates with a higher humidity value than recommended by the wood supplier.
- Never install wood which is too dry (<7% humidity). It can expand at higher humidity and cause damage.
- Do not install if the walls and ceilings of the area are not dry (e.g. after plastering or painting etc.)
- Do not dilute the adhesive.
- Never apply on a substrate which is not protected against rising damp. If necessary apply a moisture sealer such as Soudal EPR-31P.

Liability
The content of this technical data sheet is the result of tests, monitoring and experience. It is general in nature and does not constitute any liability. It is the responsibility of the user to determine by his own tests whether the product is suitable for the application.